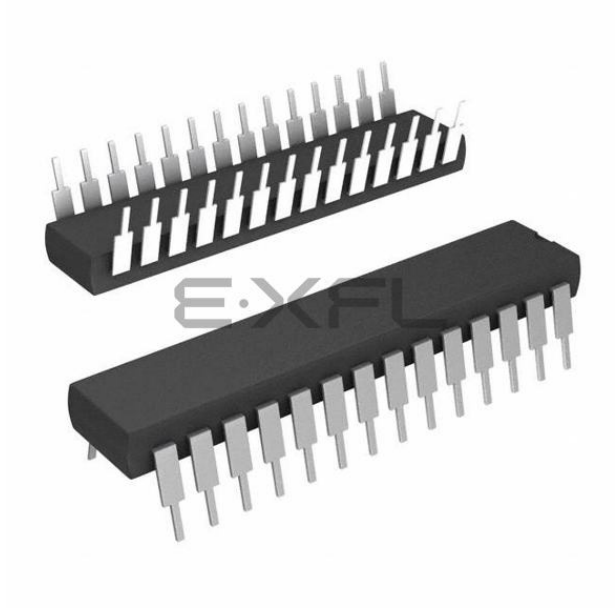

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 17x10b; D/A 1x5b, 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1716-i-sp

TABLE 3-11: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 10											
50Ch — 510h	—	Unimplemented								—	—
511h	OPA1CON	OPA1EN	OPA1SP	—	OPA1UG	—	—	OPA1PCH<1:0>		00-0 --00	00-0 --00
512h — 514h	—	Unimplemented								—	—
515h	OPA2CON	OPA2EN	OPA2SP	—	OPA2UG	—	—	OPA2PCH<1:0>		00-0 --00	00-0 --00
516h — 51Fh	—	Unimplemented								—	—
Bank 11											
58Ch to 59Fh	—	Unimplemented								—	—
Bank 12											
60Ch to 616h	—	Unimplemented								—	—
617h	PWM3DCL	PWM3DC<1:0>		—	—	—	—	—	—	xx-- ----	uu-- ----
618h	PWM3DCH	PWM3DCH<7:0>								xxxx xxxx	uuuu uuuu
619h	PWM3CON	PWM3EN	—	PWM3OUT	PWM3POL	—	—	—	—	0-x0 ----	u-uu ----
61Ah	PWM4DCL	PWM4DCL<1:0>		—	—	—	—	—	—	xx-- ----	uu-- ----
61Bh	PWM4DCH	PWM4DCH<7:0>								xxxx xxxx	uuuu uuuu
61Ch	PWM4CON	PWM4EN	—	PWM4OUT	PWM4POL	—	—	—	—	0-x0 ----	u-uu ----
61Dh — 61Fh	—	Unimplemented								—	—
Bank 13											
68Ch to 690h	—	Unimplemented								—	—
691h	COG1PHR	—	—	COG Rising Edge Phase Delay Count Register						--xx xxxx	--uu uuuu
692h	COG1PHF	—	—	COG Falling Edge Phase Delay Count Register						--xx xxxx	--uu uuuu
693h	COG1BLKR	—	—	COG Rising Edge Blanking Count Register						--xx xxxx	--uu uuuu
694h	COG1BLKF	—	—	COG Falling Edge Blanking Count Register						--xx xxxx	--uu uuuu
695h	COG1DBR	—	—	COG Rising Edge Dead-band Count Register						--xx xxxx	--uu uuuu
696h	COG1DBF	—	—	COG Falling Edge Dead-band Count Register						--xx xxxx	--uu uuuu
697h	COG1CON0	G1EN	G1LD	—	G1CS<1:0>		G1MD<2:0>			00-0 0000	00-0 0000
698h	COG1CON1	G1RDBS	G1FDBS	—	—	G1POLD	G1POLC	G1POLB	G1POLA	00-- 0000	00-- 0000
699h	COG1RIS	G1RIS7	G1RIS6	G1RIS5	G1RIS4	G1RIS3	G1RIS2	G1RIS1	G1RIS0	0000 0000	-000 0000
69Ah	COG1RSIM	G1RSIM7	G1RSIM6	G1RSIM5	G1RSIM4	G1RSIM3	G1RSIM2	G1RSIM1	G1RSIM0	0000 0000	-000 0000
69Bh	COG1FIS	G1FIS7	G1FIS6	G1FIS5	G1FIS4	G1FIS3	G1FIS2	G1FIS1	G1FIS0	0000 0000	-000 0000
69Ch	COG1FSIM	G1FSIM7	G1FSIM6	G1FSIM5	G1FSIM4	G1FSIM3	G1FSIM2	G1FSIM1	G1FSIM0	0000 0000	-000 0000
69Dh	COG1ASD0	G1ASE	G1ARSEN	G1ASDBD<1:0>		G1ASDAC<1:0>		—	—	0001 01--	0001 01--
69Eh	COG1ASD1	—	—	—	—	G1AS3E	G1AS2E	G1AS1E	G1AS0E	---- 0000	---- 0000
69Fh	COG1STR	G1SDATD	G1SDATC	G1SDATB	G1SDATA	G1STRD	G1STRC	G1STRB	G1STRA	0000 0001	0000 0001

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: Unimplemented, read as '1'.

2: Unimplemented on PIC16(L)F1713/6.

4.0 DEVICE CONFIGURATION

Device configuration consists of Configuration Words, Code Protection and Device ID.

4.1 Configuration Words

There are several Configuration Word bits that allow different oscillator and memory protection options. These are implemented as Configuration Word 1 at 8007h and Configuration Word 2 at 8008h.

Note:	The $\overline{\text{DEBUG}}$ bit in Configuration Words is managed automatically by device development tools including debuggers and programmers. For normal device operation, this bit should be maintained as a '1'.

REGISTER 4-2: CONFIG2: CONFIGURATION WORD 2

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
LVP(1)	$\overline{\text{DEBUG}}$(2)	$\overline{\text{LPBOR}}$	BORV(3)	STVREN	PLLEN
bit 13					bit 8

R/P-1	U-1	U-1	U-1	U-1	R/P-1	R/P-1	R/P-1
ZCDDIS	—	—	—	—	PPS1WAY	WRT<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	-n = Value when blank or after Bulk Erase

bit 13 **LVP:** Low-Voltage Programming Enable bit(1)
1 = Low-voltage programming enabled
0 = High-voltage on $\overline{\text{MCLR}}$ must be used for programming

bit 12 **$\overline{\text{DEBUG}}$:** In-Circuit Debugger Mode bit(2)
1 = In-Circuit Debugger disabled, ICSPCLK and ICSPDAT are general purpose I/O pins
0 = In-Circuit Debugger enabled, ICSPCLK and ICSPDAT are dedicated to the debugger

bit 11 **$\overline{\text{LPBOR}}$:** Low-Power BOR Enable bit
1 = Low-Power Brown-out Reset is disabled
0 = Low-Power Brown-out Reset is enabled

bit 10 **BORV:** Brown-out Reset Voltage Selection bit(3)
1 = Brown-out Reset voltage (V_{BOR}), low trip point selected.
0 = Brown-out Reset voltage (V_{BOR}), high trip point selected.

bit 9 **STVREN:** Stack Overflow/Underflow Reset Enable bit
1 = Stack Overflow or Underflow will cause a Reset
0 = Stack Overflow or Underflow will not cause a Reset

bit 8 **PLLEN:** PLL Enable bit
1 = 4xPLL enabled
0 = 4xPLL disabled

bit 7 **ZCDDIS:** ZCD Disable bit
1 = ZCD disabled. ZCD can be enabled by setting the ZCDSEN bit of ZCDCON
0 = ZCD always enabled

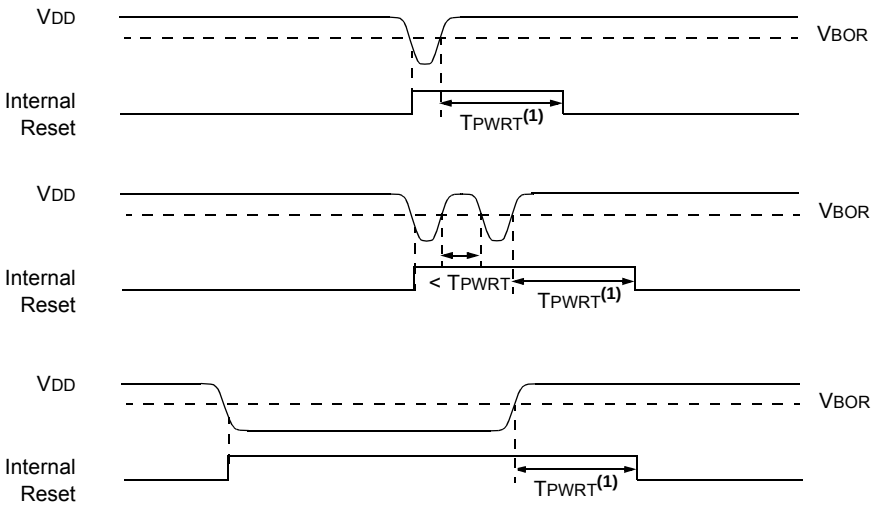
bit 6-3 **Unimplemented:** Read as '1'

bit 2 **PPS1WAY**: PPSLOCK Bit One-Way Set Enable bit
1 = The PPSLOCK bit can only be set once after an unlocking sequence is executed; once PPSLOCK is set, all future changes to PPS registers are prevented
0 = The PPSLOCK bit can be set and cleared as needed (provided an unlocking sequence is executed)

bit 1-0 **WRT<1:0>:** Flash Memory Self-Write Protection bits
4 kW Flash memory
11 = Write protection off
10 = 000h to 1FFh write protected, 200h to FFFh may be modified by PMCON control
01 = 000h to 7FFh write protected, 800h to FFFh may be modified by PMCON control
00 = 000h to FFFh write protected, no addresses may be modified by PMCON control

Note 1: The LVP bit cannot be programmed to '0' when Programming mode is entered via LVP.
2: The $\overline{\text{DEBUG}}$ bit in Configuration Words is managed automatically by device development tools including debuggers and programmers. For normal device operation, this bit should be maintained as a '1'.
3: See V_{BOR} parameter for specific trip point voltages.

FIGURE 5-2: BROWN-OUT SITUATIONS



Note 1: TPWRT delay only if $\overline{\text{PWRTE}}$ bit is programmed to '0'.

5.3 Register Definitions: BOR Control

REGISTER 5-1: BORCON: BROWN-OUT RESET CONTROL REGISTER

R/W-1/u	R/W-0/u	U-0	U-0	U-0	U-0	U-0	R-q/u
SBOREN	BORFS(1)	—	—	—	—	—	BORRDY
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7 **SBOREN:** Software Brown-out Reset Enable bit
If BOREN <1:0> in Configuration Words ≠ 01:
SBOREN is read/write, but has no effect on the BOR.
If BOREN <1:0> in Configuration Words = 01:
1 = BOR Enabled
0 = BOR Disabled

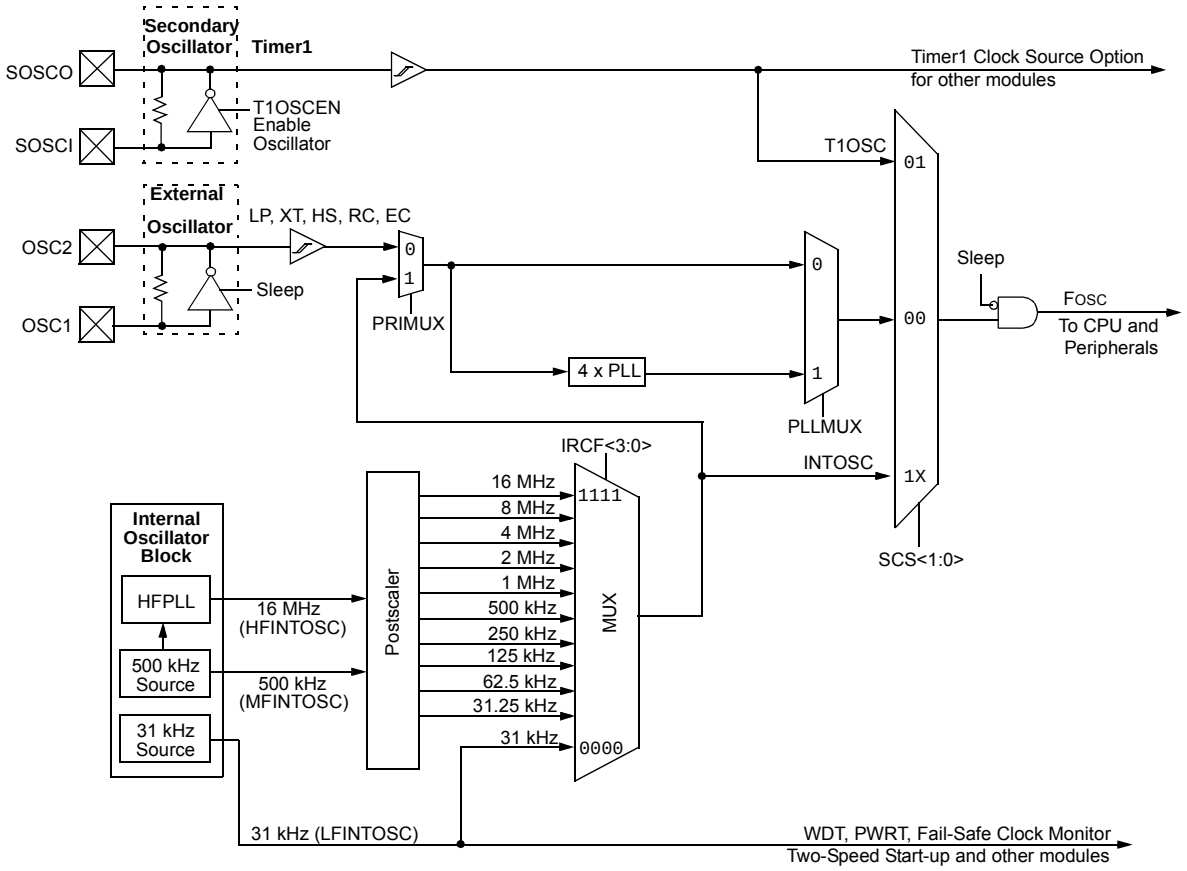
bit 6 **BORFS:** Brown-out Reset Fast Start bit(1)
If BOREN<1:0> = 11 (Always on) or BOREN<1:0> = 00 (Always off)
BORFS is Read/Write, but has no effect.
If BOREN <1:0> = 10 (Disabled in Sleep) or BOREN<1:0> = 01 (Under software control):
1 = Band gap is forced on always (covers sleep/wake-up/operating cases)
0 = Band gap operates normally, and may turn off

bit 5-1 **Unimplemented:** Read as '0'

bit 0 **BORRDY:** Brown-out Reset Circuit Ready Status bit
1 = The Brown-out Reset circuit is active
0 = The Brown-out Reset circuit is inactive

Note 1: BOREN<1:0> bits are located in Configuration Words.

FIGURE 6-1: SIMPLIFIED PIC® MCU CLOCK SOURCE BLOCK DIAGRAM



Inputs				Outputs	
SCS	FOSC<2:0>	PLLEN or SPLLEN	IRCF	PRIMUX	PLLMUX
=00	=100	0	x	1	0
		1	=1110	1	1
			≠1110	1	0
	≠100	0	x	0	0
		1	x	0	1
≠00	X	X	X	X	X

6.2.1.4 4x PLL

The oscillator module contains a 4x PLL that can be used with both external and internal clock sources to provide a system clock source. The input frequency for the 4x PLL must fall within specifications. See the PLL Clock Timing Specifications in Table 34-9.

The 4x PLL may be enabled for use by one of two methods:

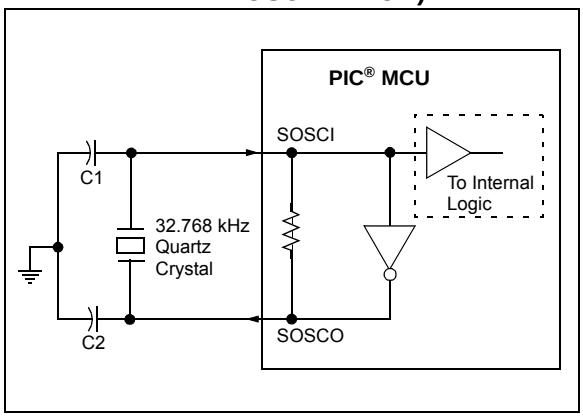
1. Program the PLLEN bit in Configuration Words to a '1'.
2. Write the SPLLEN bit in the OSCCON register to a '1'. If the PLLEN bit in Configuration Words is programmed to a '1', then the value of SPLLEN is ignored.

6.2.1.5 Secondary Oscillator

The secondary oscillator is a separate crystal oscillator that is associated with the Timer1 peripheral. It is optimized for timekeeping operations with a 32.768 kHz crystal connected between the SOSCO and SOSCI device pins.

The secondary oscillator can be used as an alternate system clock source and can be selected during run-time using clock switching. Refer to **Section 6.3 "Clock Switching"** for more information.

FIGURE 6-5: QUARTZ CRYSTAL OPERATION (SECONDARY OSCILLATOR)



Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.

2: Always verify oscillator performance over the VDD and temperature range that is expected for the application.

3: For oscillator design assistance, reference the following Microchip Application Notes:

- AN826, "*Crystal Oscillator Basics and Crystal Selection for rfPIC® and PIC® Devices*" (DS00826)
- AN849, "*Basic PIC® Oscillator Design*" (DS00849)
- AN943, "*Practical PIC® Oscillator Analysis and Design*" (DS00943)
- AN949, "*Making Your Oscillator Work*" (DS00949)
- TB097, "*Interfacing a Micro Crystal MS1V-T1K 32.768 kHz Tuning Fork Crystal to a PIC16F690/SS*" (DS91097)
- AN1288, "*Design Practices for Low-Power External Oscillators*" (DS01288)

8.0 POWER-DOWN MODE (SLEEP)

The Power-down mode is entered by executing a SLEEP instruction.

Upon entering Sleep mode, the following conditions exist:

1. WDT will be cleared but keeps running, if enabled for operation during Sleep.
2. $\overline{PD}$ bit of the STATUS register is cleared.
3. $\overline{TO}$ bit of the STATUS register is set.
4. CPU clock is disabled.
5. 31 kHz LFINTOSC is unaffected and peripherals that operate from it may continue operation in Sleep.
6. Timer1 and peripherals that operate from Timer1 continue operation in Sleep when the Timer1 clock source selected is:
   - LFINTOSC
   - T1CKI
   - Secondary oscillator
7. ADC is unaffected, if the dedicated FRC oscillator is selected.
8. I/O ports maintain the status they had before SLEEP was executed (driving high, low or high-impedance).
9. Resets other than WDT are not affected by Sleep mode.

Refer to individual chapters for more details on peripheral operation during Sleep.

To minimize current consumption, the following conditions should be considered:

- I/O pins should not be floating
- External circuitry sinking current from I/O pins
- Internal circuitry sourcing current from I/O pins
- Current draw from pins with internal weak pull-ups
- Modules using 31 kHz LFINTOSC
- Modules using secondary oscillator

I/O pins that are high-impedance inputs should be pulled to V_{DD} or V_{SS} externally to avoid switching currents caused by floating inputs.

Examples of internal circuitry that might be sourcing current include modules such as the DAC and FVR modules. See **Section 22.0 “Operational Amplifier (OPA) Modules”** and **Section 14.0 “Fixed Voltage Reference (FVR)”** for more information on these modules.

8.1 Wake-up from Sleep

The device can wake-up from Sleep through one of the following events:

1. External Reset input on $\overline{MCLR}$ pin, if enabled
2. BOR Reset, if enabled
3. POR Reset
4. Watchdog Timer, if enabled
5. Any external interrupt
6. Interrupts by peripherals capable of running during Sleep (see individual peripheral for more information)

The first three events will cause a device Reset. The last three events are considered a continuation of program execution. To determine whether a device Reset or wake-up event occurred, refer to **Section 5.12 “Determining the Cause of a Reset”**.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is prefetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be enabled. Wake-up will occur regardless of the state of the GIE bit. If the GIE bit is disabled, the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is enabled, the device executes the instruction after the SLEEP instruction, the device will then call the Interrupt Service Routine. In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.

19.0 CONFIGURABLE LOGIC CELL (CLC)

The Configurable Logic Cell (CLCx) provides programmable logic that operates outside the speed limitations of software execution. The logic cell takes up to 32 input signals and, through the use of configurable gates, reduces the 32 inputs to four logic lines that drive one of eight selectable single-output logic functions.

Input sources are a combination of the following:

- I/O pins
- Internal clocks
- Peripherals
- Register bits

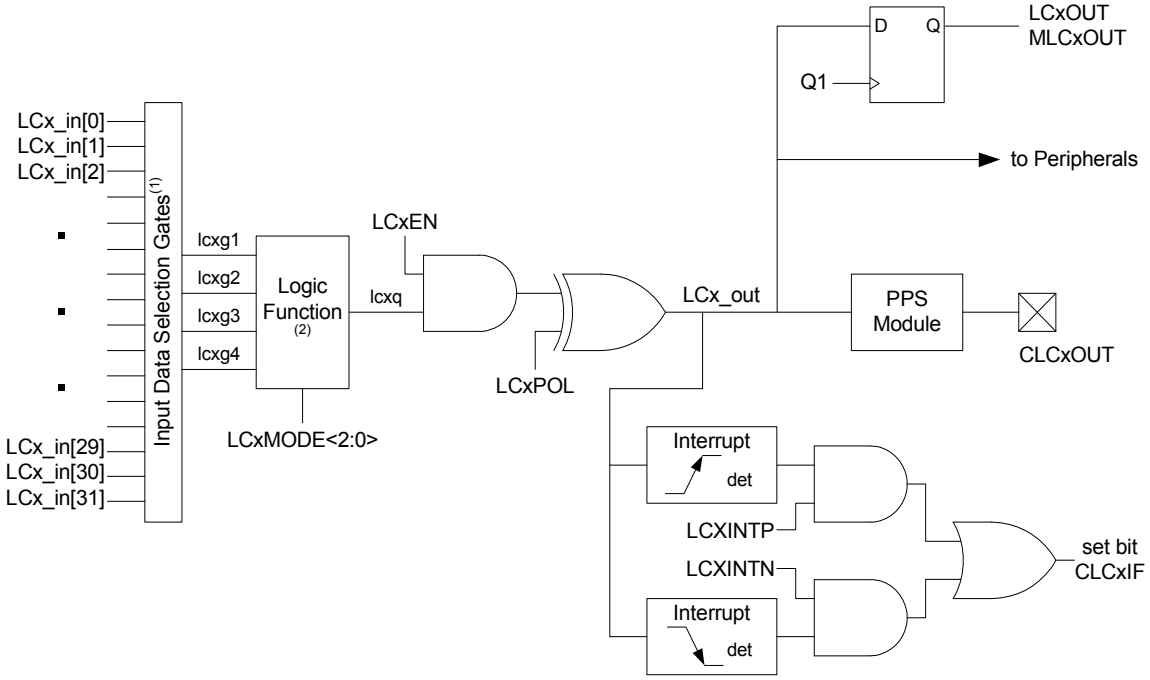
The output can be directed internally to peripherals and to an output pin.

Refer to Figure 19-1 for a simplified diagram showing signal flow through the CLCx.

Possible configurations include:

- Combinatorial Logic
  - AND
  - NAND
  - AND-OR
  - AND-OR-INVERT
  - OR-XOR
  - OR-XNOR
- Latches
  - S-R
  - Clocked D with Set and Reset
  - Transparent D with Set and Reset
  - Clocked J-K with Reset

FIGURE 19-1: CLCx SIMPLIFIED BLOCK DIAGRAM



Note 1: See Figure 19-2: Input Data Selection and Gating.
2: See Figure 19-3: Programmable Logic Functions.

26.1 Timer1 Operation

The Timer1 module is a 16-bit incrementing counter which is accessed through the TMR1H:TMR1L register pair. Writes to TMR1H or TMR1L directly update the counter.

When used with an internal clock source, the module is a timer and increments on every instruction cycle. When used with an external clock source, the module can be used as either a timer or counter and increments on every selected edge of the external source.

Timer1 is enabled by configuring the TMR1ON and TMR1GE bits in the T1CON and T1GCON registers, respectively. Table 26-1 displays the Timer1 enable selections.

TABLE 26-1: TIMER1 ENABLE SELECTIONS

TMR1ON	TMR1GE	Timer1 Operation
0	0	Off
0	1	Off
1	0	Always On
1	1	Count Enabled

26.2 Clock Source Selection

The TMR1CS<1:0> and T1OSCEN bits of the T1CON register are used to select the clock source for Timer1. Table 26-2 displays the clock source selections.

26.2.1 INTERNAL CLOCK SOURCE

When the internal clock source is selected, the TMR1H:TMR1L register pair will increment on multiples of FOSC as determined by the Timer1 prescaler.

When the FOSC internal clock source is selected, the Timer1 register value will increment by four counts every instruction clock cycle. Due to this condition, a 2 LSB error in resolution will occur when reading the Timer1 value. To utilize the full resolution of Timer1, an asynchronous input signal must be used to gate the Timer1 clock input.

The following asynchronous sources may be used:

- Asynchronous event on the T1G pin to Timer1 gate
- C1 or C2 comparator input to Timer1 gate

26.2.2 EXTERNAL CLOCK SOURCE

When the external clock source is selected, the Timer1 module may work as a timer or a counter.

When enabled to count, Timer1 is incremented on the rising edge of the external clock input T1CKI, which can be synchronized to the microcontroller system clock or can run asynchronously.

When used as a timer with a clock oscillator, an external 32.768 kHz crystal can be used in conjunction with the dedicated internal oscillator circuit.

Note: In Counter mode, a falling edge must be registered by the counter prior to the first incrementing rising edge after any one or more of the following conditions:

- Timer1 enabled after POR
- Write to TMR1H or TMR1L
- Timer1 is disabled
- Timer1 is disabled (TMR1ON = 0) when T1CKI is high then Timer1 is enabled (TMR1ON=1) when T1CKI is low.

TABLE 26-2: CLOCK SOURCE SELECTIONS

TMR1CS<1:0>	T1OSCEN	Clock Source
11	x	LFINTOSC
10	0	External Clocking on T1CKI Pin
01	x	System Clock (FOSC)
00	x	Instruction Clock (FOSC/4)

28.0 ZERO-CROSS DETECTION (ZCD) MODULE

The ZCD module detects when an A/C signal crosses through the ground potential. The actual zero-crossing threshold is the zero-crossing reference voltage, ZCPINV, which is typically 0.75V above ground.

The connection to the signal to be detected is through a series current limiting resistor. The module applies a current source or sink to the ZCD pin to maintain a constant voltage on the pin, thereby preventing the pin voltage from forward biasing the ESD protection diodes. When the applied voltage is greater than the reference voltage, the module sinks current. When the applied voltage is less than the reference voltage, the module sources current. The current source and sink action keeps the pin voltage constant over the full range of the applied voltage. The ZCD module is shown in the simplified block diagram Figure 28-2.

The ZCD module is useful when monitoring an A/C waveform for, but not limited to, the following purposes:

- A/C period measurement
- Accurate long term time measurement
- Dimmer phase delayed drive
- Low EMI cycle switching

28.1 External Resistor Selection

The ZCD module requires a current limiting resistor in series with the external voltage source. The impedance and rating of this resistor depends on the external source peak voltage. Select a resistor value that will drop all of the peak voltage when the current through the resistor is nominally 300 µA (refer to Equation 28-1 and Figure 28-1). Make sure that the ZCD I/O pin internal weak pull-up is disabled so it does not interfere with the current source and sink.

EQUATION 28-1: EXTERNAL RESISTOR

$$R_{SERIES} = \frac{V_{PEAK}}{3\times10^{-4}}$$

FIGURE 28-1: EXTERNAL VOLTAGE

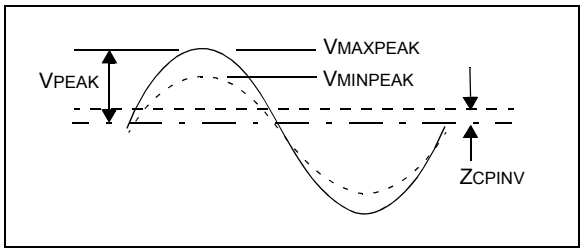
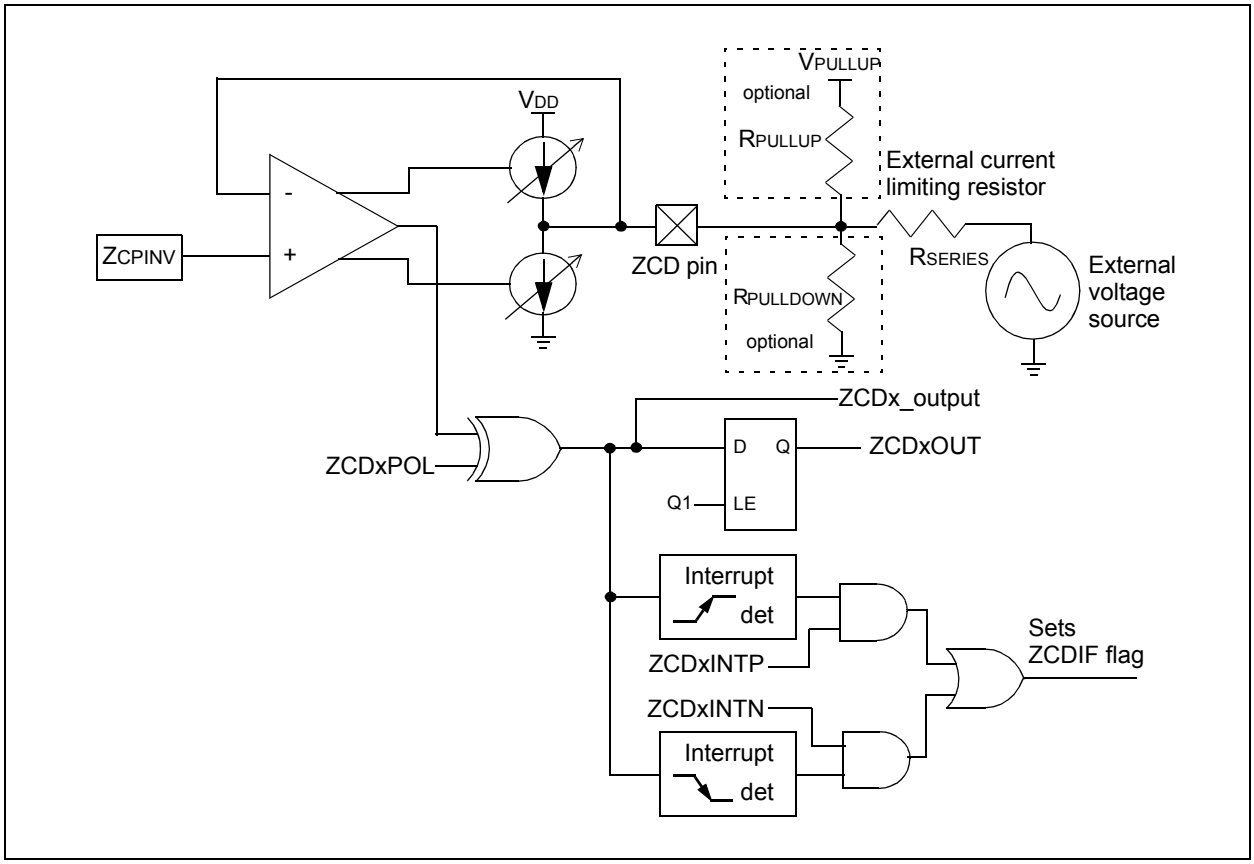


FIGURE 28-2: SIMPLIFIED ZCD BLOCK DIAGRAM



29.4 Register Definitions: CCP Control

REGISTER 29-1: CCPxCON: CCPx CONTROL REGISTER

U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—	—	DCxB<1:0>		CCPxM<3:0>			
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Reset
'1' = Bit is set	'0' = Bit is cleared	

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **DCxB<1:0>:** PWM Duty Cycle Least Significant bits

Capture mode:
Unused

Compare mode:
Unused

PWM mode:
These bits are the two LSbs of the PWM duty cycle. The eight MSbs are found in CCPRxL.

bit 3-0 **CCPxM<3:0>:** CCPx Mode Select bits

11xx = PWM mode

1011 = Compare mode: Auto-conversion Trigger (sets CCPxIF bit), starts ADC conversion if TRIGSEL = CCPx (see Register 21-3)
1010 = Compare mode: generate software interrupt only
1001 = Compare mode: clear output on compare match (set CCPxIF)
1000 = Compare mode: set output on compare match (set CCPxIF)

0111 = Capture mode: every 16th rising edge
0110 = Capture mode: every 4th rising edge
0101 = Capture mode: every rising edge
0100 = Capture mode: every falling edge

0011 = Reserved
0010 = Compare mode: toggle output on match
0001 = Reserved
0000 = Capture/Compare/PWM off (resets CCPx module)

REGISTER 30-5: SSP1MSK: SSP MASK REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
MSK<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-1 **MSK<7:1>:** Mask bits
1 = The received address bit n is compared to SSPADD<n> to detect I^2C address match
0 = The received address bit n is not used to detect I^2C address match

bit 0 **MSK<0>:** Mask bit for I^2C Slave mode, 10-bit Address
I^2C Slave mode, 10-bit address (SSPM<3:0> = 0111 or 1111):
1 = The received address bit 0 is compared to SSPADD<0> to detect I^2C address match
0 = The received address bit 0 is not used to detect I^2C address match
I^2C Slave mode, 7-bit address, the bit is ignored

REGISTER 30-6: SSP1ADD: MSSP ADDRESS AND BAUD RATE REGISTER (I^2C MODE)

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
ADD<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

Master mode:

bit 7-0 **ADD<7:0>:** Baud Rate Clock Divider bits
SCL pin clock period = ((ADD<7:0> + 1) *4)/FOSC

10-Bit Slave mode – Most Significant Address Byte:

bit 7-3 **Not used:** Unused for Most Significant Address Byte. Bit state of this register is a "don't care". Bit pattern sent by master is fixed by I^2C specification and must be equal to '11110'. However, those bits are compared by hardware and are not affected by the value in this register.

bit 2-1 **ADD<2:1>:** Two Most Significant bits of 10-bit address

bit 0 **Not used:** Unused in this mode. Bit state is a "don't care".

10-Bit Slave mode – Least Significant Address Byte:

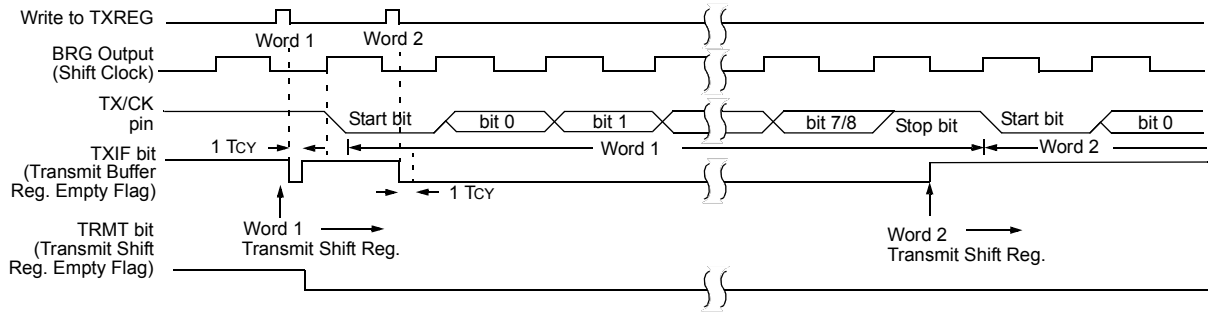
bit 7-0 **ADD<7:0>:** Eight Least Significant bits of 10-bit address

7-Bit Slave mode:

bit 7-1 **ADD<7:1>:** 7-bit address

bit 0 **Not used:** Unused in this mode. Bit state is a "don't care".

FIGURE 31-4: ASYNCHRONOUS TRANSMISSION (BACK-TO-BACK)



Note: This timing diagram shows two consecutive transmissions.

TABLE 31-1: SUMMARY OF REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BAUD1CON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	349
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	83
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	84
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	87
RC1STA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	348
RxyPPS	—	—	—	RxyPPS<4:0>					137
SP1BRGL	SP1BRG<7:0>								350*
SP1BRGH	SP1BRG<15:8>								350*
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	125
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	130
TX1REG	EUSART Transmit Data Register								339*
TX1STA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	347

Legend: — = unimplemented location, read as '0'. Shaded cells are not used for asynchronous transmission.

* Page provides register information.

31.4.1 AUTO-BAUD DETECT

The EUSART module supports automatic detection and calibration of the baud rate.

In the Auto-Baud Detect (ABD) mode, the clock to the BRG is reversed. Rather than the BRG clocking the incoming RX signal, the RX signal is timing the BRG. The Baud Rate Generator is used to time the period of a received 55h (ASCII "U") which is the Sync character for the LIN bus. The unique feature of this character is that it has five rising edges including the Stop bit edge.

Setting the ABDEN bit of the BAUDCON register starts the auto-baud calibration sequence. While the ABD sequence takes place, the EUSART state machine is held in Idle. On the first rising edge of the receive line, after the Start bit, the SPBRG begins counting up using the BRG counter clock as shown in Figure 31-6. The fifth rising edge will occur on the RX pin at the end of the eighth bit period. At that time, an accumulated value totaling the proper BRG period is left in the SPBRGH, SPBRGL register pair, the ABDEN bit is automatically cleared and the RCIF interrupt flag is set. The value in the RCREG needs to be read to clear the RCIF interrupt. RCREG content should be discarded. When calibrating for modes that do not use the SPBRGH register the user can verify that the SPBRGL register did not overflow by checking for 00h in the SPBRGH register.

The BRG auto-baud clock is determined by the BRG16 and BRGH bits as shown in Table 31-6. During ABD, both the SPBRGH and SPBRGL registers are used as a 16-bit counter, independent of the BRG16 bit setting. While calibrating the baud rate period, the SPBRGH and SPBRGL registers are clocked at 1/8th the BRG base clock rate. The resulting byte measurement is the average bit time when clocked at full speed.

Note 1: If the WUE bit is set with the ABDEN bit, auto-baud detection will occur on the byte following the Break character (see **Section 31.4.3 "Auto-Wake-up on Break"**).

2: It is up to the user to determine that the incoming character baud rate is within the range of the selected BRG clock source. Some combinations of oscillator frequency and EUSART baud rates are not possible.

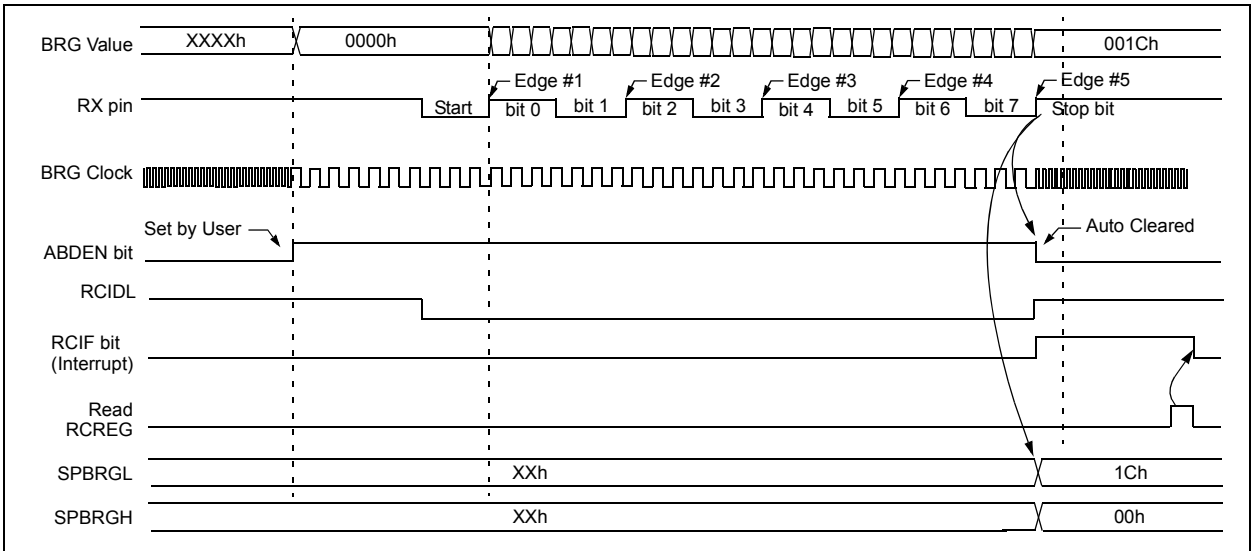
3: During the auto-baud process, the auto-baud counter starts counting at one. Upon completion of the auto-baud sequence, to achieve maximum accuracy, subtract 1 from the SPBRGH:SPBRGL register pair.

TABLE 31-6: BRG COUNTER CLOCK RATES

BRG16	BRGH	BRG Base Clock	BRG ABD Clock
0	0	FOSC/64	FOSC/512
0	1	FOSC/16	FOSC/128
1	0	FOSC/16	FOSC/128
1	1	FOSC/4	FOSC/32

Note: During the ABD sequence, SPBRGL and SPBRGH registers are both used as a 16-bit counter, independent of the BRG16 setting.

FIGURE 31-6: AUTOMATIC BAUD RATE CALIBRATION



Note 1: The ABD sequence requires the **EUSART** module to be configured in Asynchronous mode.

TABLE 34-2: SUPPLY CURRENT (I_{DD})(1,2) (CONTINUED)

PIC16LF1713/6		Standard Operating Conditions (unless otherwise stated)					
PIC16F1713/6							
Param No.	Device Characteristics	Min.	Typ†	Max.	Units	Conditions	
						V_{DD}	Note
D017		—	115	175	μA	1.8	F_{OSC} = 500 kHz, MFINTOSC mode
		—	135	210	μA	3.0	
D017		—	150	230	μA	2.3	F_{OSC} = 500 kHz, MFINTOSC mode
		—	170	250	μA	3.0	
		—	215	310	μA	5.0	
D019		—	0.7	1.3	mA	1.8	F_{OSC} = 16 MHz, HFINTOSC mode
		—	1.2	1.9	mA	3.0	
D019		—	1.1	1.8	mA	2.3	F_{OSC} = 16 MHz, HFINTOSC mode
		—	1.3	2	mA	3.0	
		—	1.4	2.1	mA	5.0	
D020		—	2.5	3.3	mA	3.0	F_{OSC} = 32 MHz, HFINTOSC mode
		—	3	4.1	mA	3.6	
D020		—	2.6	3.8	mA	3.0	F_{OSC} = 32 MHz, HFINTOSC mode
		—	2.7	3.9	mA	5.0	
D022		—	2.3	3.1	mA	3.0	F_{OSC} = 32 MHz, HS Oscillator mode (**Note 5**)
		—	2.8	3.9	mA	3.6	
D022		—	2.4	3.6	mA	3.0	F_{OSC} = 32 MHz HS Oscillator mode (**Note 5**)
		—	2.6	3.8	mA	5.0	

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all I_{DD} measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{DD}; $\overline{MCLR}$ = V_{DD}; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: For RC oscillator configurations, current through REXT is not included. The current by the formula IR = V_{DD}/2REXT (mA) with REXT in kΩ.

4: FVR and BOR are disabled.

5: 8 MHz clock with 4x PLL enabled.

TABLE 34-3: POWER-DOWN CURRENTS (I_{PD})(1,2) (CONTINUED)

PIC16LF1713/6			Operating Conditions: (unless otherwise stated) Low-Power Sleep Mode					
PIC16F1713/6			Low-Power Sleep Mode, VREGPM = 1					
Param No.	Device Characteristics	Min.	Typ†	Max. +85°C	Max. +125°C	Units	Conditions	
							V_{DD}	Note
D030		—	250	—	—	µA	1.8	ADC Current **(Note 3)**, conversion in progress
		—	250	—	—	µA	3.0	
D030		—	280	—	—	µA	2.3	ADC Current **(Note 3)**, conversion in progress
		—	280	—	—	µA	3.0	
		—	280	—	—	µA	5.0	
D031		—	250	650	—	µA	3.0	Op Amp (High-power)
D031		—	250	650	—	µA	3.0	Op Amp (High-power)
		—	350	850	—	µA	5.0	
D032		—	250	600	—	µA	1.8	Comparator, CxSP = 0
		—	300	650	—	µA	3.0	
D032		—	280	600	—	µA	2.3	Comparator, CxSP = 0 VREGPM = 0
		—	300	650	—	µA	3.0	
		—	310	650	—	µA	5.0	

* These parameters are characterized but not tested.

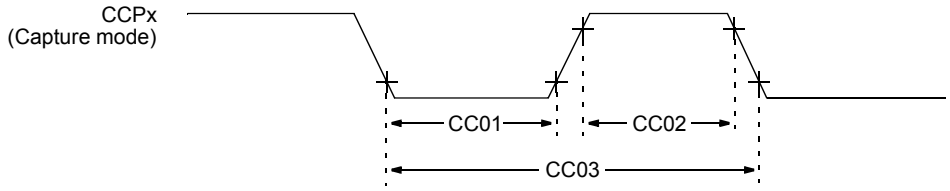
† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral current is the sum of the base I_{PD} and the additional current consumed when this peripheral is enabled. The peripheral Δ current can be determined by subtracting the base I_{DD} or I_{PD} current from this limit. Max values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to V_{SS}.

3: ADC clock source is FRC.

FIGURE 34-11: CAPTURE/COMPARE/PWM TIMINGS (CCP)



Note: Refer to Figure 34-4 for load conditions.

TABLE 34-13: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP)

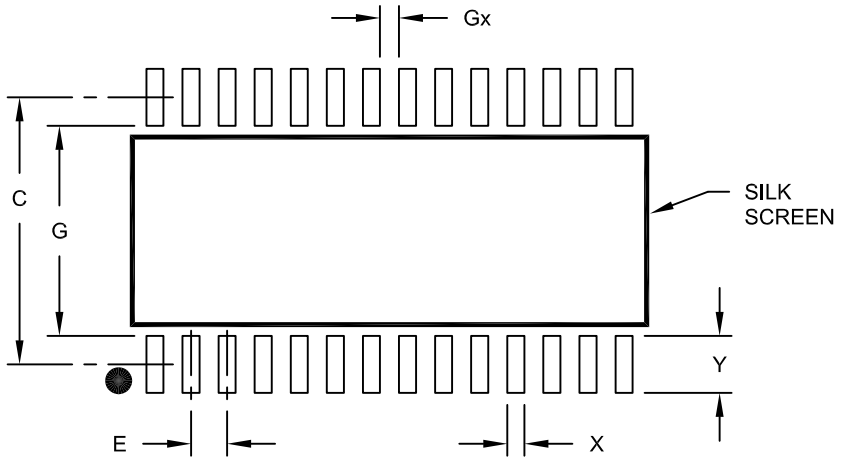
Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C								
Param No.	**Sym.**	**Characteristic**		**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
CC01*	TccL	CCPx Input Low Time	No Prescaler	0.5TCY + 20	—	—	ns	
			With Prescaler	20	—	—	ns	
CC02*	TccH	CCPx Input High Time	No Prescaler	0.5TCY + 20	—	—	ns	
			With Prescaler	20	—	—	ns	
CC03*	TccP	CCPx Input Period		$\frac{3T_{CY} + 40}{*N}$	—	—	ns	N = prescale value

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

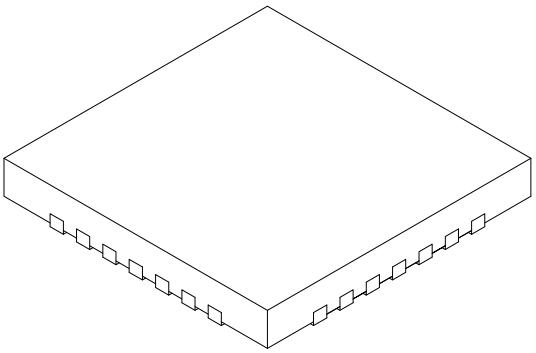
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

28-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 4x4x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.40 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.127 REF	
Overall Width	E		4.00 BSC	
Exposed Pad Width	E2	2.55	2.65	2.75
Overall Length	D		4.00 BSC	
Exposed Pad Length	D2	2.55	2.65	2.75
Contact Width	b	0.15	0.20	0.25
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-152A Sheet 2 of 2

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